



Material Content Data Sheet



Sales Product Name	TLE4209A			Issued		28. August 2013		
MA#	MA000982386							
Package	PG-DIP-8-4			Weight*		519.10 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.347	1.22	1.22	12226	12226
leadframe	inorganic material	phosphorus	7723-14-0	0.053	0.01		103	
	non noble metal	zinc	7440-66-6	0.213	0.04		411	
	non noble metal	iron	7439-89-6	4.266	0.82		8219	
	non noble metal	copper	7440-50-8	173.237	33.37	34.24	333725	342458
wire	noble metal	gold	7440-57-5	0.611	0.12	0.12	1177	1177
encapsulation	organic material	carbon black	1333-86-4	1.622	0.31		3124	
	inorganic material	antimonytrioxide	1309-64-4	6.487	1.25		12496	
	plastics	brominated resin	-	6.487	1.25		12496	
	plastics	epoxy resin	-	66.487	12.81		128082	
	inorganic material	silicondioxide	60676-86-0	243.246	46.87	62.49	468591	624789
leadfinish	non noble metal	tin	7440-31-5	7.496	1.44	1.44	14440	14440
plating	noble metal	silver	7440-22-4	0.832	0.16	0.16	1603	1603
glue	plastics	epoxy resin	-	0.515	0.10		992	
	noble metal	silver	7440-22-4	1.202	0.23	0.33	2315	3307
*deviation	< 10%				Sum in total:		100,00	1000000

Important Remarks:

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